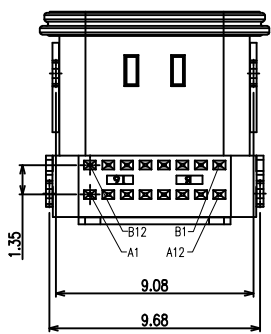
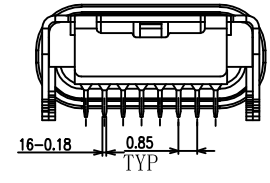
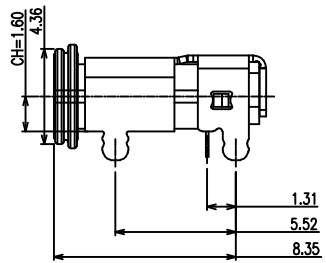
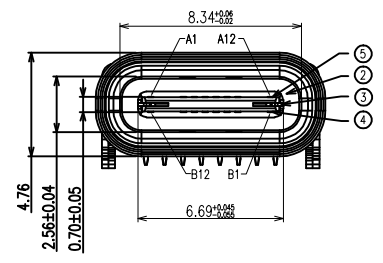
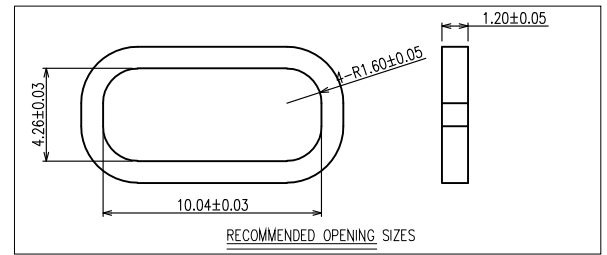
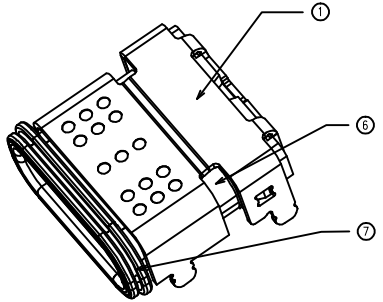


DATE COTE  
XX XX X  
15:2015年  
44:第44周  
1: 周末  
2: 周一  
.....  
7: 周六



REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
X1			????	07/11'20	陈海波
X2			ADD PACKING SURFACE	07/24'20	Chen haibo
X3		③	UPDATE DWG	09/04'20	Chen haibo
X4		④	CHANGE TOLERANC	11/05'20	Chen haibo
X5		⑤	ADD WATERPROOF GRADE	06/07'22	Chen haibo

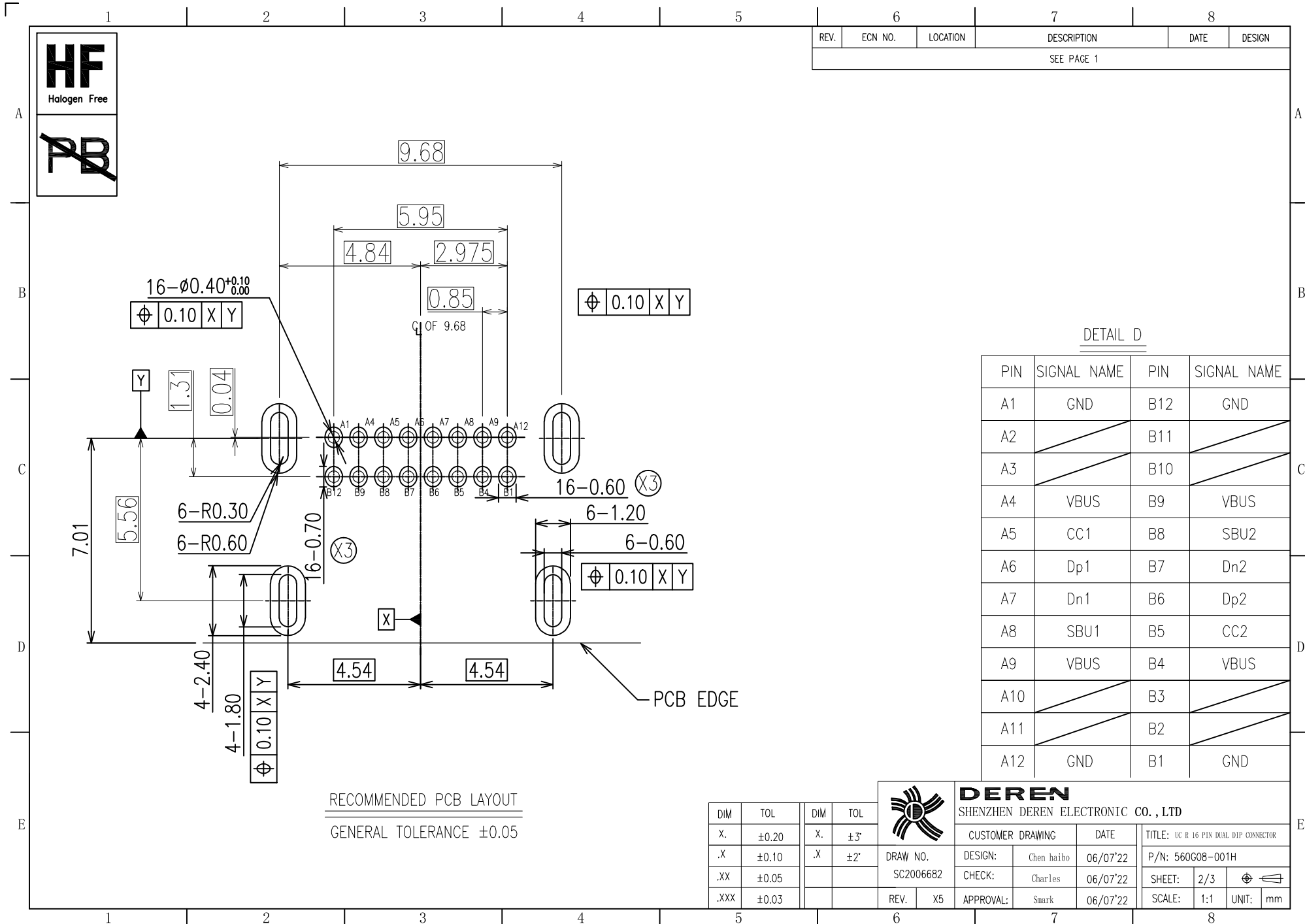
NOTES :

- ELECTRICAL :
  - CONTACT CURRENT RATING :  
5.0A FOR VBUS (Pins A4,A9,B4,B9)  
6.25A FOR GND (Pins A1,A12,B1,B12)
  - INSULATION RESISTANCE :  
100 MEGAOHMS. AT 300VDC.
  - DIELECTRIC WITHSTANDING VOLTAGE :300VAC, 0.5mA .
  - LOW LEVEL CONTACT RESISTANCE :  
INITIAL 40mΩ MAX. AFTER 50mΩ MAX.
- MECHANICAL CHARACTERISTICS :
  - INSERTION FORCE :5N~20N .
  - EXTRACTION FORCE : 8N~20N FROM 1 TO 30 CYCLES.  
6N~20N FROM 31 TO 10000 CYCLES.
  - DURABILITY : 10,000 MATING CYCLES.
  - OPERATING TEMPERATURE :-55°C TO +85°C
- WATERPROOF GRADE : IPX4
- PART NUMBER INFORMATION:

560G08-001H  
 HF:HALOGEN FREE  
 FLOW CODE  
 PIN: 16PIN  
 SERIES CODE: USB TYPE C

ITEM	PART NAME	Q'TY	MATERIAL	REMARK
⑦	SEALING RING	1 PCS	SILICA GEL	UL94V-0, COLOR: BLACK
⑥	INNER SHELL	1 PCS	STAINLESS	N
⑤	TOP CONTACT	1 SET	COPPER ALLOY	50u" MIN. Ni UNDER PLATING. 80u" MIN. MATTE TIN PLATING ON SOLDER AREA.
④	BOTTOM CONTACT	1 SET	COPPER ALLOY	5u" MIN. Au ON CONTACT AREA.
③	Mid-PLATE	1 PCS	STAINLESS	50u" MIN. SOLDERABLE Ni PLATING OVER ALL.
②	HOUSING	1 PCS	THERMAL PLASTIC	UL94V-0, COLOR: BLACK
①	OUT SHELL	1 PCS	STAINLESS	50u" MIN. SOLDERABLE Ni PLATING OVERALL.

DIM	TOL	DIM	TOL	<p><b>DEREN</b> SHENZHEN DEREN ELECTRONIC CO., LTD</p>	CUSTOMER DRAWING		DATE	TITLE: UC REC 16P CH=1.6 R/A WATERPROOF DUAL DIP CONN.
.X	±0.30	.X	±3'		DESIGN:	Chen haibo	06/07'22	P/N:560G08-001H
.X	±0.25	.X	±2'		CHECK:	Charles	06/07'22	SHEET: 1/3
.XX	±0.15				REV.	X5	06/07'22	SCALE: 1:1
.XXX	±0.10				APPROVAL:	Smark	06/07'22	UNIT: mm



REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
SEE PAGE 1					

DETAIL D

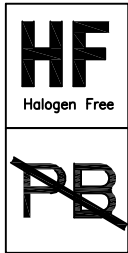
PIN	SIGNAL NAME	PIN	SIGNAL NAME
A1	GND	B12	GND
A2		B11	
A3		B10	
A4	VBUS	B9	VBUS
A5	CC1	B8	SBU2
A6	Dp1	B7	Dn2
A7	Dn1	B6	Dp2
A8	SBU1	B5	CC2
A9	VBUS	B4	VBUS
A10		B3	
A11		B2	
A12	GND	B1	GND

RECOMMENDED PCB LAYOUT  
 GENERAL TOLERANCE ±0.05

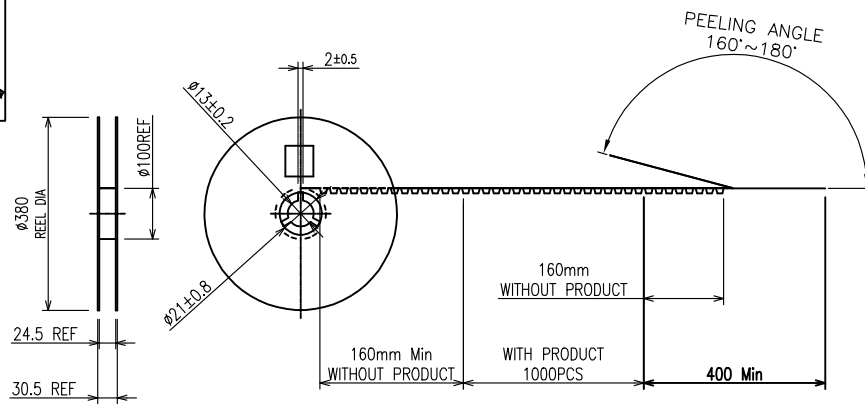
DIM	TOL	DIM	TOL
.X	±0.20	.X	±3'
.X	±0.10	.X	±2'
.XX	±0.05		
.XXX	±0.03		

**DEREN**  
 SHENZHEN DEREN ELECTRONIC CO., LTD

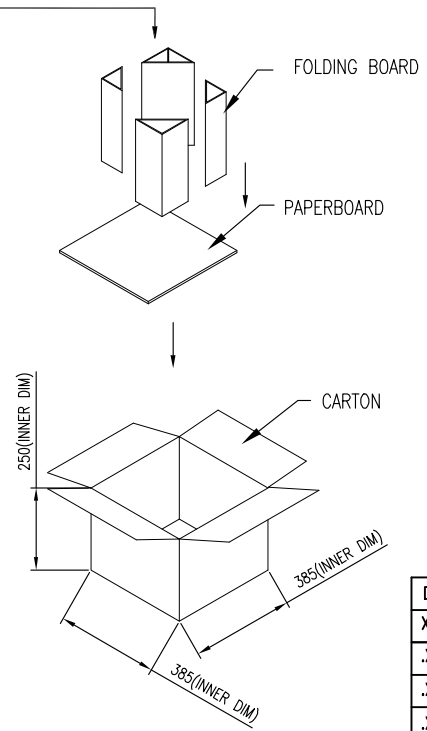
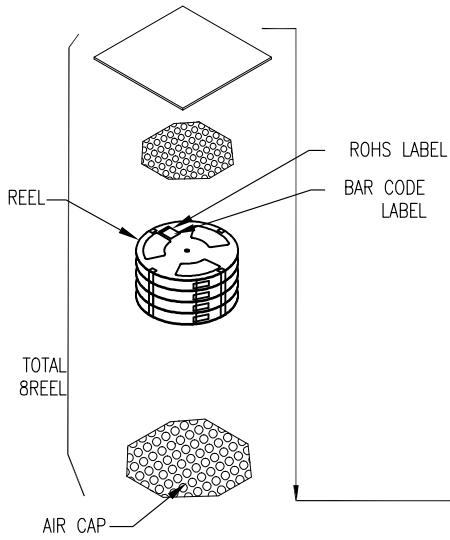
DRAW NO. SC2006682		DESIGN: Chen haibo	DATE: 06/07'22	TITLE: UC R 16 PIN DUAL DIP CONNECTOR
REV. X5	CHECK: Charles	DATE: 06/07'22	P/N: 560G08-001H	
APPROVAL: Smark	DATE: 06/07'22	SHEET: 2/3		UNIT: mm
SCALE: 1:1				



GATHER MATERIAL DIRECTION      INPUT MATERIAL DIRECTION



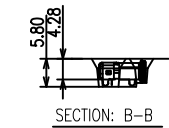
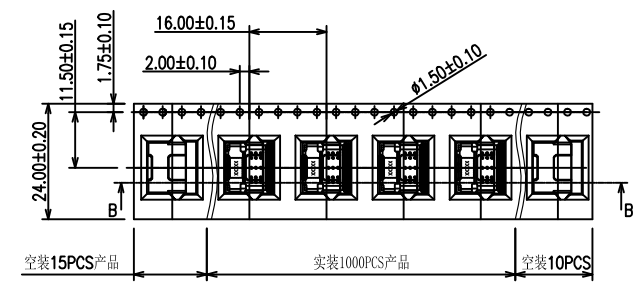
REEL WIDTH



REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
SEE PAGE 1					

GATHER MATERIAL DIRECTION      INPUT MATERIAL DIRECTION

END      START



- NOTES : (FOR REEL)  
 PACKAGING MATERIAL IN PLASTIC, RUBBER, INK, PIGMENT AND PAINT MUST MEET CONTROLLED SUBSTANCES SPEC PER 230-702.  
 \* CADMIUM AND CADMIUM COMPOUNDS NOT TO EXCEED: 5 PPM.  
 \* LEAD, CADMIUM, CHROM VI AND MERCURY NOT TO EXCEED: 100 PPM (COMBINED).  
 \* CARRIER TAPES, COVER TAPES, REELS AND TAPED COMPONENTS MUST MEET THE REQUIREMENTS DEFINED PER EIA-481-B.
- MATERIAL :  
 COVER TAPE : ANTISTATIC P.S T=0.05±0.01 ,COLOR: :CLEAR  
 CARRIER TAPE : ANTISTATIC P.S T=0.40mm ±0.05 ,  
 REEL : PS UL94V-0  
 SHIPPING BOX: CORRUGATED FIBER
  - QUANTITY : SEE TABLE
  - PEELING RESISTANCE : 10gf~130gf (for 12~56mm)
  - PEELING SPEED : 300mm/MINUTES

1000	8	8000	560G08-001H
PCS/ REEL	REEL/ BOX	PCS/ BOX	PART NUMBER
<b>DEREN</b> SHENZHEN DEREN ELECTRONIC CO., LTD			
CUSTOMER DRAWING		DATE	TITLE: UC REC 16P CH=1.6 R/A WATERPROOF DUAL DIP CONN.
DRAW NO. SC2006682	DESIGN: Chen haibo	06/07'22	P/N:560G08-001H
REV. X5	CHECK: Charles	06/07'22	SHEET: 3/3
	APPROVAL: Smark	06/07'22	SCALE: 1:1 UNIT: mm

DIM	TOL	DIM	TOL
X.	±0.30	X.	±3'
.X	±0.25	.X	±2'
.XX	±0.15		
.XXX	±0.10		